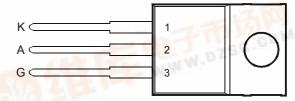
TIC116 SERIES SILICON CONTROLLED RECTIFIERS

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APRIL 1971 - REVISED JUNE 2000

- 8 A Continuous On-State Current SD. GDM
- 80 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I_{GT} of 20 mA

TO-220 PACKAGE (TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDC1ACA

absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT	
	TIC116D		400	12	
Repetitive peak off-state voltage	TIC116M	V	600	V	
	TIC116S	V _{DRM}	700	V	
	TIC116N	THE WAY	800		
Repetitive peak reverse voltage	TIC116D		400		
	TIC116M	V	600	V	
	TIC116S	V _{RRM}	700		
	TIC116N		800		
Continuous on-state current at (or below) 70°C case temperature (see Note 1)			8	Α	
Average on-state current (180° conduction angle) at (or below) 70°C case temperature		1	5	А	
(see Note 2)		I _{T(AV)}	3		
Surge on-state current at (or below) 25°C case temperature (see Note 3)		I _{TM}	80	Α	
Peak positive gate current (pulse width ≤ 300 μs)		I _{GM}	3	Α	
Peak gate power dissipation (pulse width ≤ 300 μs)		P _{GM}	5	W	
Average gate power dissipation (see Note 4)		P _{G(AV)}	1.074	W	
Operating case temperature range		T _C	-40 to +110	°C	
Storage temperature range		T _{stg}	-40 to +125	°C	
Lead temperature 1.6 mm from case for 10 seconds		TL	230	°C	

- NOTES: 1. These values apply for continuous dc operation with resistive load. Above 70°C derate linearly to zero at 110°C.
 - 2. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 70°C derate linearly to zero at 110°C.
 - 3. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
 - 4. This value applies for a maximum averaging time of 20 ms.





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electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT	
I _{DRM}	Repetitive peak off-state current	V _D = rated V _{DRM}		T _C = 110°C			2	mA
I _{RRM}	Repetitive peak reverse current	V _R = rated V _{RRM}	I _G = 0	T _C = 110°C			2	mA
I _{GT}	Gate trigger current	V _{AA} = 12 V	$R_L = 100 \Omega$	t _{p(g)} ≥ 20 μs		8	20	mA
	Gate trigger voltage	$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$	T _C = - 40°C			2.5	
V _{GT}		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$			0.8	1.5	٧
		$V_{AA} = 12 \text{ V}$ $t_{p(g)} \ge 20 \mu\text{s}$	$R_L = 100 \Omega$	T _C = 110°C	0.2			
I _H	Holding current	$V_{AA} = 12 \text{ V}$ Initiating $I_T = 100 \text{ mA}$		T _C = - 40°C			100	mA
		$V_{AA} = 12 \text{ V}$ Initiating $I_T = 100 \text{ mA}$					40	
V _T	On-state voltage	I _T = 8 A	(see Note 5)				1.7	V
dv/dt	Critical rate of rise of off-state voltage	V_D = rated V_D	I _G = 0	T _C = 110°C		400		V/µs

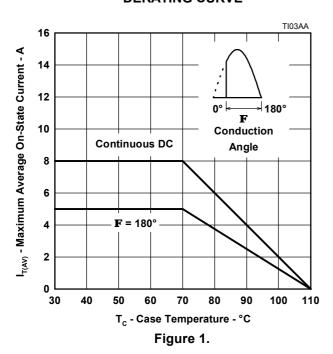
NOTE 5: This parameter must be measured using pulse techniques, t_p = 300 µs, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

thermal characteristics

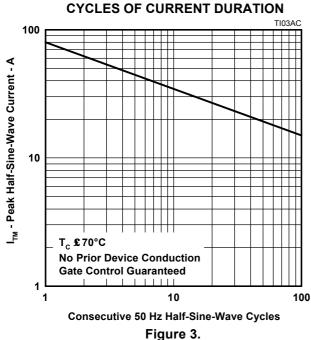
PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			3	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

THERMAL INFORMATION

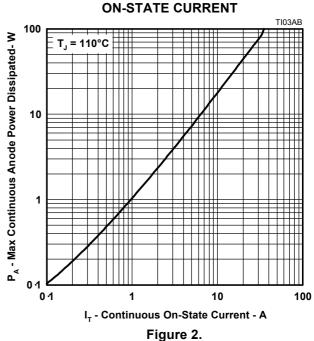
AVERAGE ON-STATE CURRENT DERATING CURVE



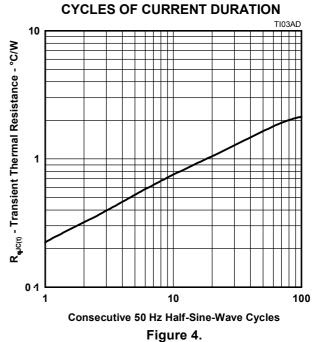
SURGE ON-STATE CURRENT vs



MAX ANODE POWER LOSS VS ON STATE CURRENT



TRANSIENT THERMAL RESISTANCE vs

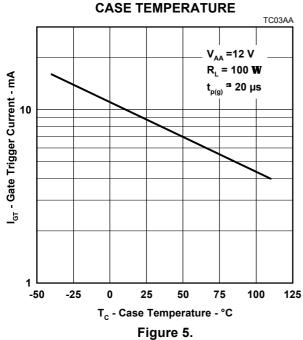




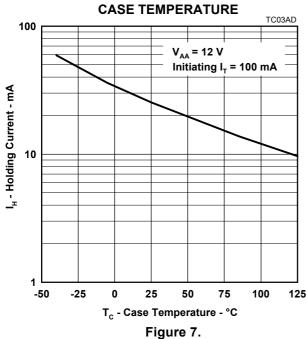
TYPICAL CHARACTERISTICS

04

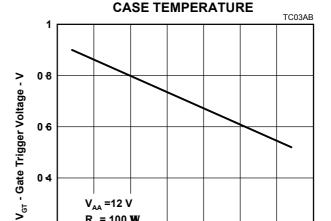
GATE TRIGGER CURRENT vs



HOLDING CURRENT vs



GATE TRIGGER VOLTAGE



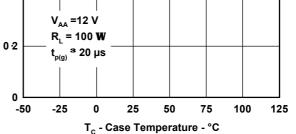
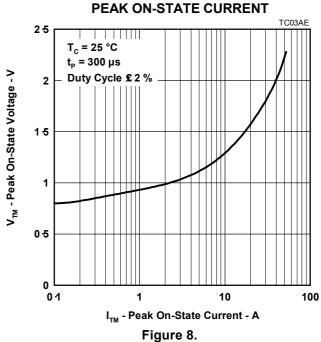


Figure 6.

PEAK ON-STATE VOLTAGE vs

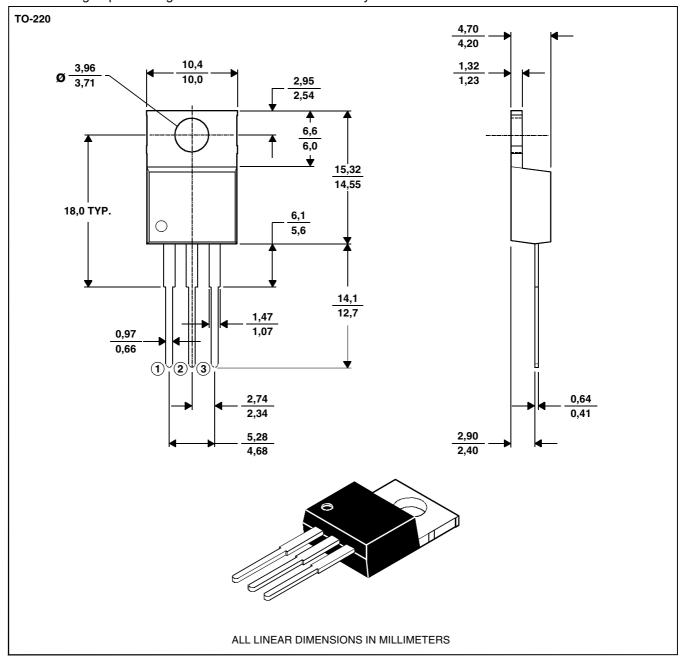


MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.



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